

# **2015 10th International Workshop on the Electromagnetic Compatibility of Integrated Circuits (EMC Compo 2015)**

**Edinburgh, United Kingdom  
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## Welcome and Keynote I

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**Welcome to EMC Compo 2015**

*(Kieran O'Leary)*

**Maxwell's Legacy — The Heart and Soul of the EMC Discipline**

*(Bob Scully)*

**No documents from this session were available at the time of publication.**

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No documents from this session were available at the time of publication.

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No documents from this session were available at the time of publication.
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No documents from this session were available at the time of publication.

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- No documents from this session were available at the time of publication.

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## System Decoupling Capacitor Selection and Placement to Minimize Radiation and Immunity Issues Part I (Workshop)

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  - B#5**     **The Power Delivery System**  
*(Kristoffer Skytte)*
  - B#5**     **Simple Test Board Measurements and Results**  
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- No documents from this session were available at the time of publication.

## System Decoupling Capacitor Selection and Placement to Minimize Radiation and Immunity Issues Part II (Workshop)

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- No documents from this session were available at the time of publication.

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*(Arnab Bhattacharya)*
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- No documents from this session were available at the time of publication.